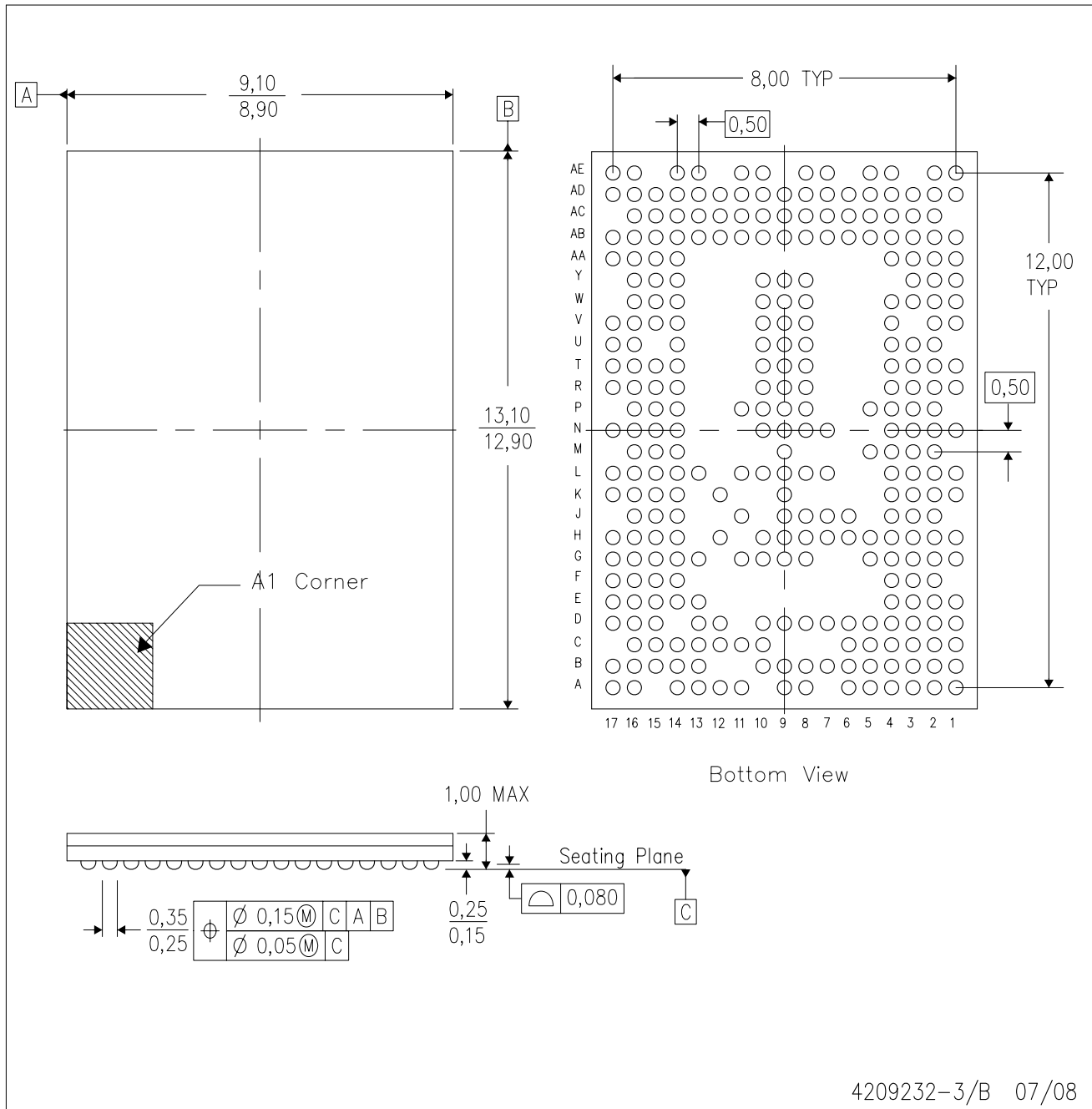


CMM (R-PBGA-N297)

PLASTIC BALL GRID ARRAY



4209232-3/B 07/08

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Flip chip application only.
 - Lead-free die bump and solder ball.

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